

Data Sheet



Title: **100mm SCR Wafers**

Issue A
Date 04-Jan-01
Sheet 1 of 2

100mm Silicon Controlled Rectifier Wafers

Features

- Glass passivated
- Corner gate and side gate
- 100% probe tested
- Supplied diced on tape or un-diced
- Evaporated contacts for superior heat sinking on soldering or wire bonding.

Electrical Characteristics

Part Number	V _{drm} & V _{rrm}	I _{drm} & I _{rrm}	V _{gt}	I _{gt}	I _t	V _t	I _h	di / dt	dv / dt
	Minimum Repetitive peak on-state forward and reverse	Maximum Peak off-state forward and reverse current @	Maximum DC gate trigger voltage	Maximum DC gate trigger current	Maximum On-state current (RMS)	Typical Peak on-state forward voltage @ I _t	Maximum DC holding current gate open	Maximum Critical rate of rise of on-state current	Maximum Critical rate of rise of off-state voltage
	V	μA	V	mA	A	V	mA	A / μsec	A / μsec
WSCR-080-0600-004	600	3	2	20	4	1.4	75	100	500
WSCR-080-1200-004	1200	3	2	20	4	1.4	75	100	500
WSCR-125-0600-012	600	5	2	20	12	1.4	75	100	500
WSCR-125-1200-012	1200	5	2	20	12	1.4	75	100	500
WSCR-180-0600-025	600	10	2	45	25	1.4	75	100	500
WSCR-180-1200-025	1200	10	2	45	25	1.4	75	100	500
WSCR-230-0600-040	600	20	2	45	40	1.4	75	100	500
WSCR-230-1200-040	1200	20	2	45	40	1.4	75	100	500
WSCR-280-0600-055	600	20	2	60	55	1.4	75	100	500
WSCR-280-1200-055	1200	20	2	60	55	1.4	75	100	500
WSCR-335-0600-070	600	20	2	60	70	1.4	75	100	500
WSCR-335-1200-070	1200	20	2	60	70	1.4	75	100	500

Notes: All parameters stated at Tamb = 25C

Mechanical Characteristics

- Nominal Back Metal Composition: Al / Ti / Ni / Ag
- Nominal Front Metal Composition: Al / Ti / Ni / Ag or Al only
- Die Dimensions: See page two
- Wafer Diameter: See page two
- Wafer Thickness: See page two
- Maximum Width of Sawing Line: 0.1mm
- Reject Ink Dot Size: tba
- Reject Ink Dot Location: tba
- Recommended Storage Condition: -50C to +125C

Data Sheet



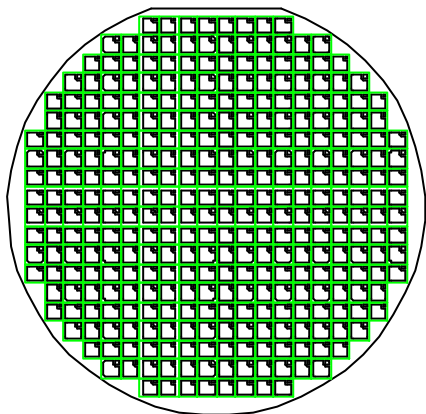
Title: **100mm SCR Wafers**

Issue A
Date 04-Jan-01
Sheet 2 of 2

100mm Silicon Controlled Rectifier Wafers

Mechanical Outline

Wafer Outline

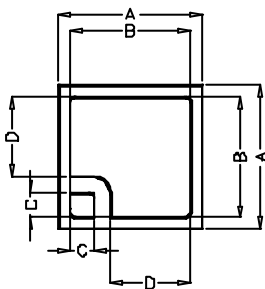


Notes:

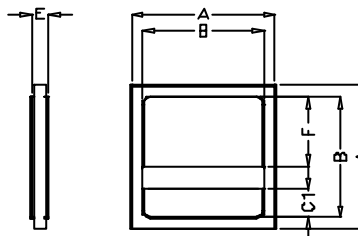
Wafer Diameter: 100 mm +/- 0.4 mm
Wafer Thickness: 350 μ m +/- 15 μ m

Die Outline

Cathode Side
Corner Gate



Cathode Side
Side Gate



Notes:

Side Gate 0.080 and 0.125" die
Corner Gate All others
General Tolerance: 0.002"
All dimensions in inches unless otherwise stated

Part Number	A	B	C	C1	D	E	F	Die / Wafer
WSCR-080-0600-004	0.080	0.065	n/a	0.009	n/a	0.014	0.045	1,575
WSCR-080-1200-004	0.080	0.065	n/a	0.009	n/a	0.014	0.045	1,575
WSCR-125-0600-012	0.125	0.104	n/a	0.023	n/a	0.014	0.060	646
WSCR-125-1200-012	0.125	0.104	n/a	0.023	n/a	0.014	0.060	646
WSCR-180-0600-025	0.180	0.141	0.028	n/a	0.099	0.014	n/a	292
WSCR-180-1200-025	0.180	0.140	0.028	n/a	0.099	0.014	n/a	292
WSCR-230-0600-040	0.230	0.190	0.040	n/a	0.135	0.014	n/a	176
WSCR-230-1200-040	0.230	0.190	0.040	n/a	0.135	0.014	n/a	176
WSCR-280-0600-055	0.280	tba	tba	n/a	tba	0.014	n/a	120
WSCR-280-1200-055	0.280	tba	tba	n/a	tba	0.014	n/a	120
WSCR-335-0600-070	0.335	0.293	0.048	n/a	0.224	0.014	n/a	80
WSCR-335-1200-070	0.335	0.293	0.048	n/a	0.224	0.014	n/a	80